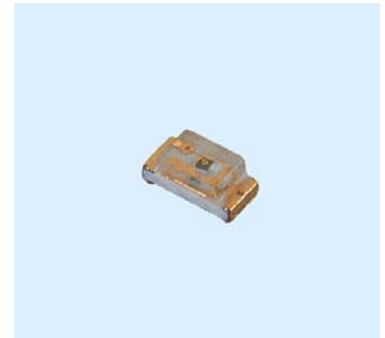# Technical Data Sheet

0603 Package Chip LED (0.6mm Height)

19-213SURC/S530-A3/TR8

Features

- Package in 8mm tape on 7″ diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow
  solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.

Descriptions

- The 19-213 SMD LED is much smaller than lead
  frame type components, thus enable smaller board
  size, higher packing density, reduced storage space
  and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for
 miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in
  telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Part No.	Chip Material	Emitted Color	Resin Color
19-213SURC/S530-A3/TR8	AlGaInP	Brilliant Red	Water Clear

Package Outline Dimensions

Polarity
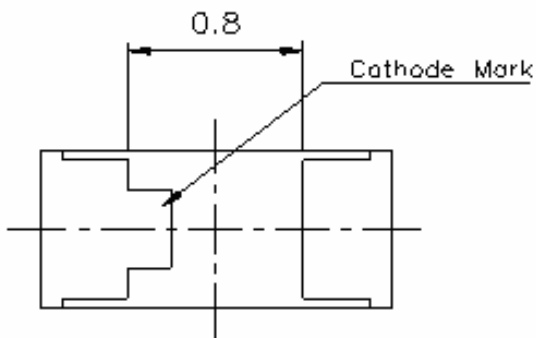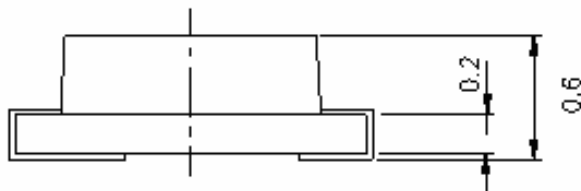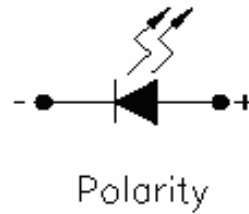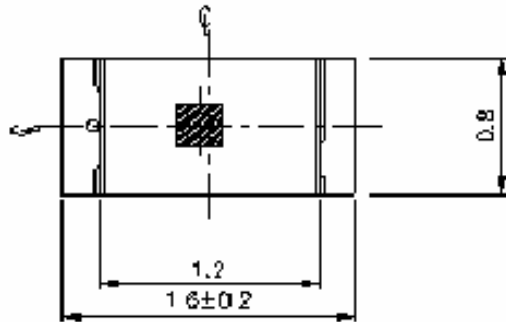
For reflow soldering (Propose)
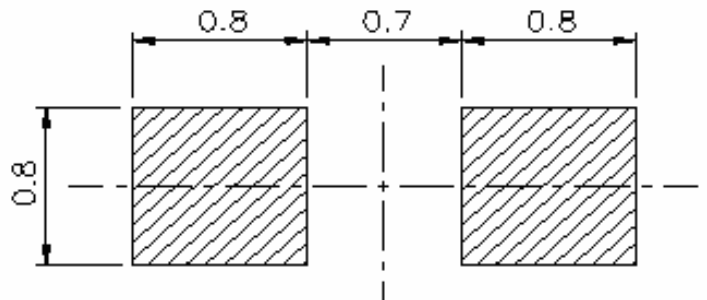
Cathode Mark

Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Power Dissipation	Pd	60	mW
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	60	mA
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	36.0	54.0	----	mcd	I_F =20mA
Viewing Angle	$2\theta 1/2$	----	120	----	deg	
Peak Wavelength	λp	----	632	----	nm	
Dominant Wavelength	λd	----	624	----	nm	
Spectrum Radiation Bandwidth	$\triangle \lambda$	----	20	----	nm	
Forward Voltage	V_F	1.70	2.00	2.40	V	
Reverse Current	I_R	----	----	10	μ A	V_R=5V

Typical Electro-Optical Characteristics Curves

Spectrum Distribution

Forward Current vs. Forward Voltage

Luminous Intensity vs. Ambient Temperature

Luminous Intensity vs Forward Current

Forward Current Derating Curve

Radiation Diagram   Ta=25°C
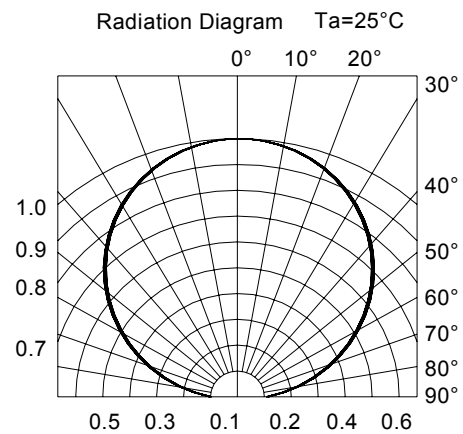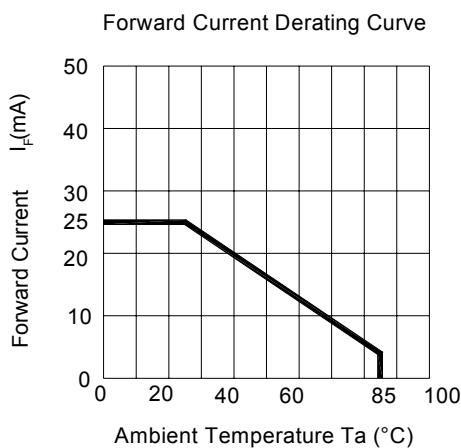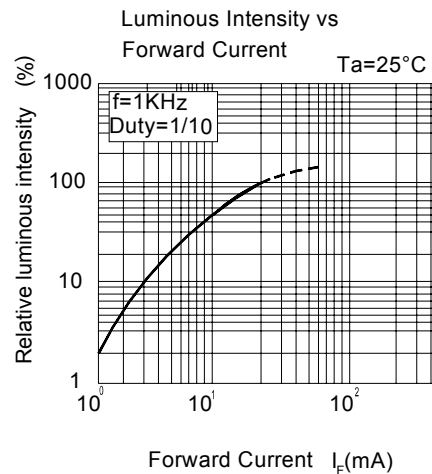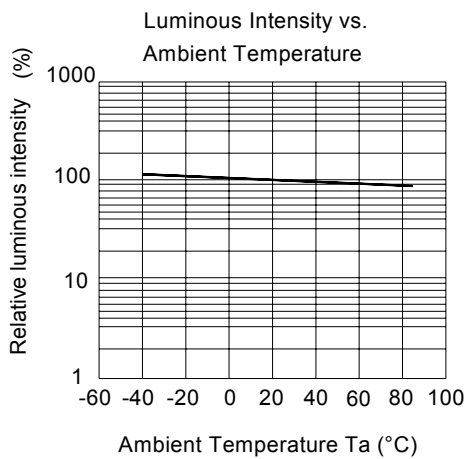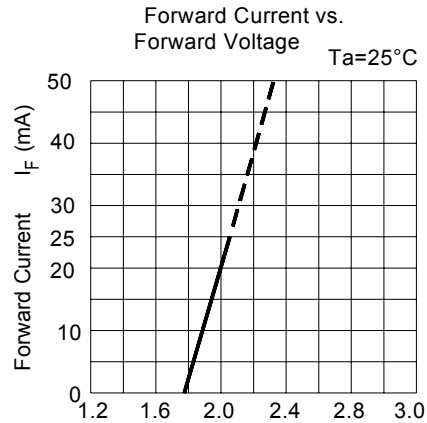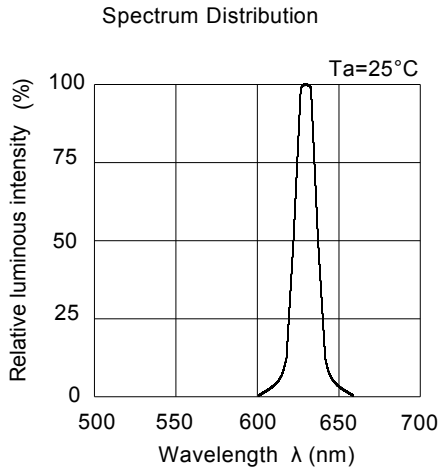
19-213SURC/S530-A3/TR8

Label explanation

CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank
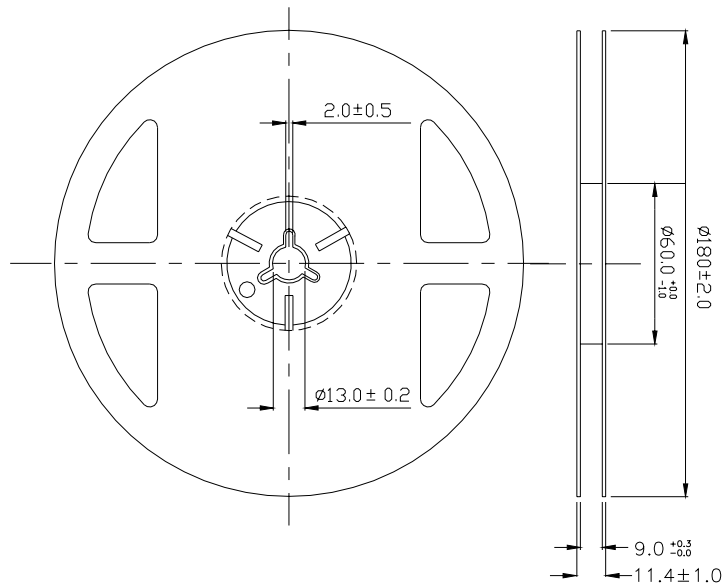
```
┌─────────────────────────────────┐
│ (Pb)  ┌──────────────┐    ◯      │
│       │  EVERLIGHT   │           │
│ CPN:  └──────────────┘           │
│ P/N : XXXXXXXXX                  │
│ ‖‖‖‖‖‖‖‖‖‖‖‖‖‖‖    ┌──────┐      │
│ XXXXXXXXXX          │ RoHS │      │
│                     └──────┘      │
│ QTY:XXX            CAT:XX         │
│ ‖‖‖‖‖‖‖‖‖‖         HUE:XX         │
│                    REF:XX         │
│ LOT NO:XXXXXXXXXXX               │
│ ‖‖‖‖‖‖‖‖‖‖‖‖‖‖                   │
│ Reference:XXXXXXXXX             │
│ ‖‖‖‖‖‖‖‖‖‖‖‖                     │
│                MADE IN TAIWAN    │
└─────────────────────────────────┘
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Reel Dimensions

Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel
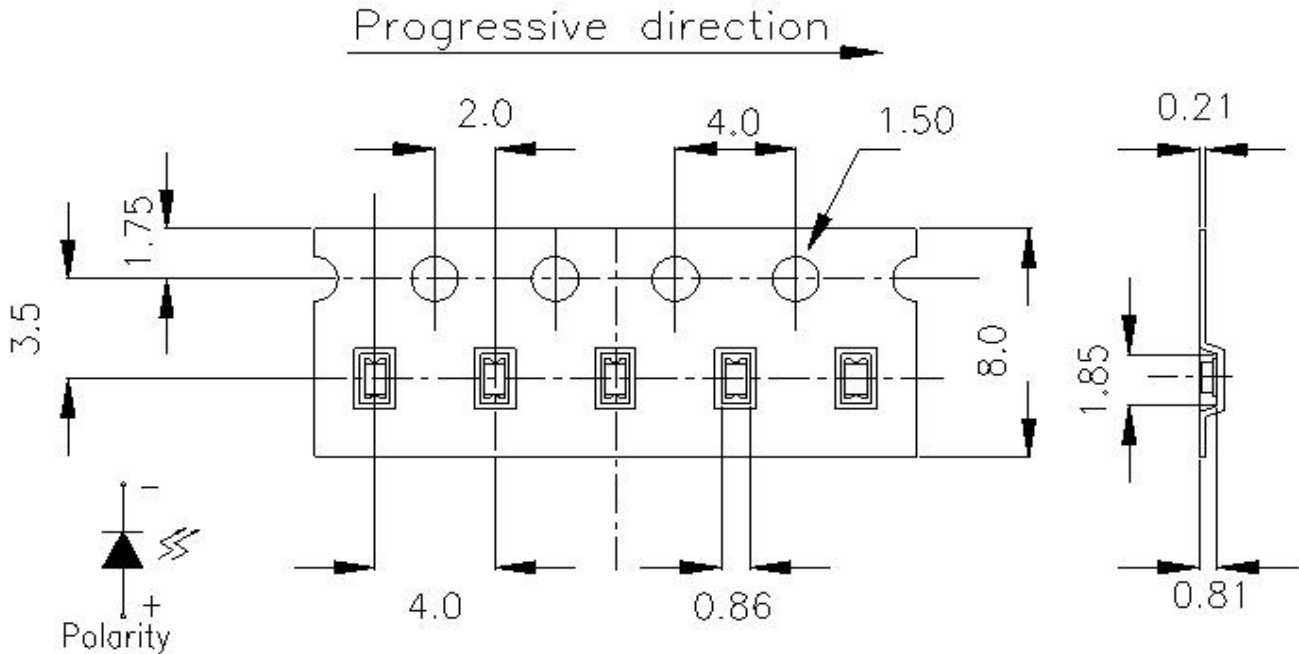
Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Moisture Resistant Packaging

Label   Aluminum moisture-proof bag   Desiccant   Label
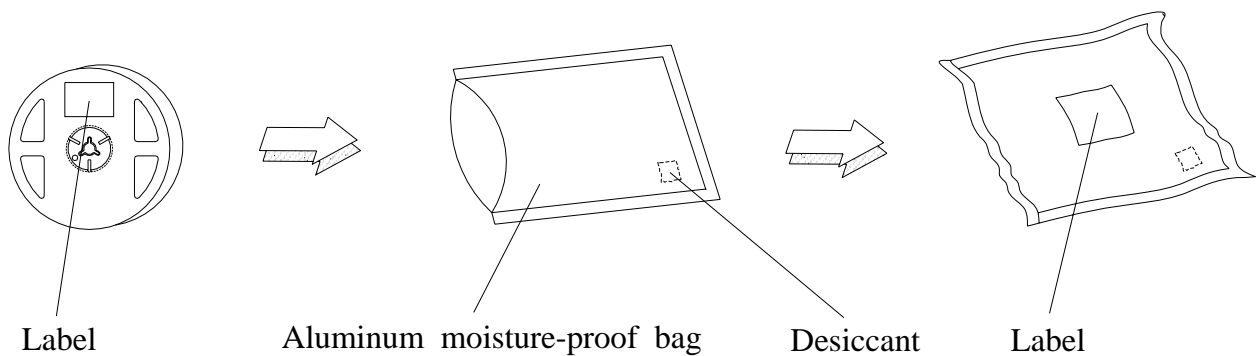
Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level：90%

LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃ / 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

   Customer must apply resistors for protection , otherwise slight voltage shift will cause big

   current change (Burn out will happen).

2. Storage

   2.1 Do not open moisture proof bag before the products are ready to use.

   2.2 Before opening the package, the LEDs should be kept at 30℃ or less and 90%RH or less.

   2.3 After opening the package: The LED's floor life is 1 year under 30℃or less and 60% RH or less.
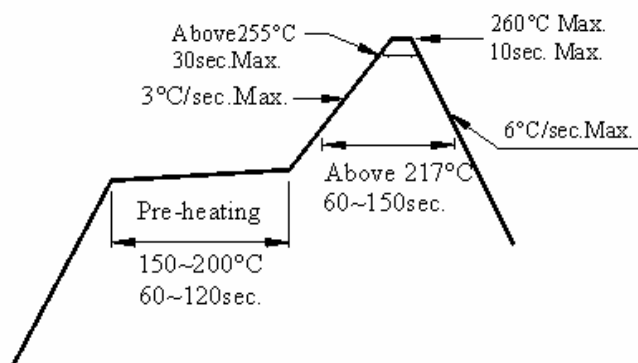
   If unused LEDs remain, it should be stored in moisture proof packages.

   2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the

   storage time, baking treatment should be performed using the following conditions.

   Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile

3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

   Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

   Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
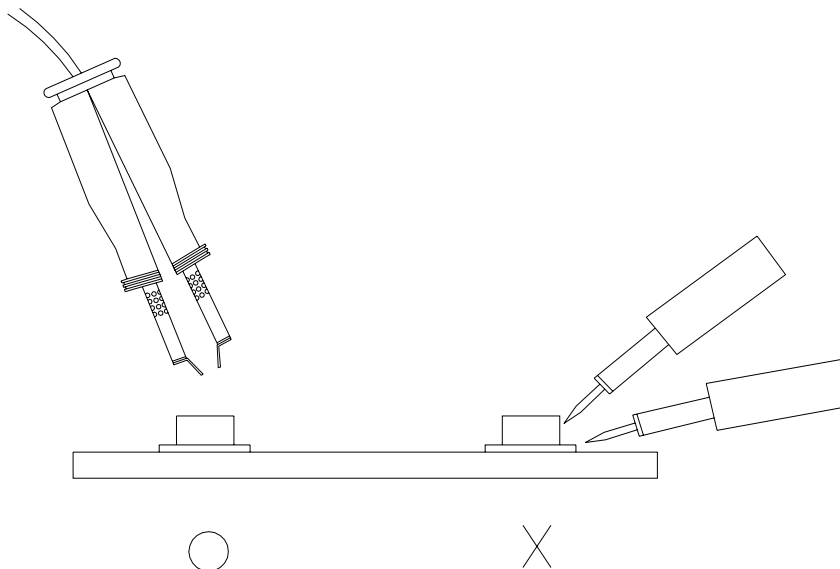
单击下面可查看定价，库存，交付和生命周期等信息

>>Everlight(亿光)